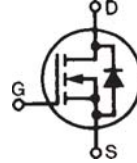


# Depletion Mode MOSFETs

## IXTH16N50D2 IXTT16N50D2

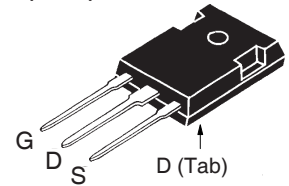
$V_{DSX} = 500V$   
 $I_{D(on)} \geq 16A$   
 $R_{DS(on)} \leq 300m\Omega$

N-Channel

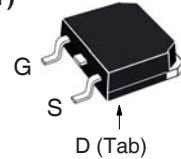


Symbol	Test Conditions	Maximum Ratings	
$V_{DSX}$	$T_J = 25^\circ C$ to $150^\circ C$	500	V
$V_{DGX}$	$T_J = 25^\circ C$ to $150^\circ C$ , $R_{GS} = 1M\Omega$	500	V
$V_{GSX}$	Continuous	$\pm 20$	V
$V_{GSM}$	Transient	$\pm 30$	V
$P_D$	$T_C = 25^\circ C$	695	W
$T_J$		- 55 ... +150	$^\circ C$
$T_{JM}$		150	$^\circ C$
$T_{stg}$		- 55 ... +150	$^\circ C$
$T_L$	1.6mm (0.062 in.) from Case for 10s	300	$^\circ C$
$T_{SOLD}$	Plastic Body for 10s	260	$^\circ C$
$M_d$	Mounting Torque (TO-247)	1.13 / 10	Nm/lb.in.
Weight	TO-247	6	g
	TO-268	4	g

TO-247 (IXTH)



TO-268 (IXTT)



G = Gate      D = Drain  
 S = Source    Tab = Drain

### Features

- Normally ON Mode
- International Standard Packages
- Molding Epoxies Meet UL94V-0 Flammability Classification

### Advantages

- Easy to Mount
- Space Savings
- High Power Density

### Applications

- Audio Amplifiers
- Start-up Circuits
- Protection Circuits
- Ramp Generators
- Current Regulators
- Active Loads

Symbol	Test Conditions ( $T_J = 25^\circ C$ , Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max.
$BV_{DSX}$	$V_{GS} = -5V$ , $I_D = 250\mu A$	500		V
$V_{GS(off)}$	$V_{DS} = 25V$ , $I_D = 4mA$	- 2.0		V
$I_{GSX}$	$V_{GS} = \pm 20V$ , $V_{DS} = 0V$			$\pm 100$ nA
$I_{DSX(off)}$	$V_{DS} = V_{DSX}$ , $V_{GS} = -5V$ $T_J = 125^\circ C$			10 $\mu A$ 150 $\mu A$
$R_{DS(on)}$	$V_{GS} = 0V$ , $I_D = 8A$ , Note 1			300 m $\Omega$
$I_{D(on)}$	$V_{GS} = 0V$ , $V_{DS} = 25V$ , Note 1	16		A

Symbol	Test Conditions ( $T_J = 25^\circ\text{C}$ , Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max.
$g_{fs}$	$V_{DS} = 30\text{V}, I_D = 8\text{A}$ , Note 1	7	12	S
$C_{iss}$	$V_{GS} = -10\text{V}, V_{DS} = 25\text{V}, f = 1\text{MHz}$		5250	pF
$C_{oss}$			515	pF
$C_{rss}$			130	pF
$t_{d(on)}$	<b>Resistive Switching Times</b> $V_{GS} = \pm 5\text{V}, V_{DS} = 250\text{V}, I_D = 8\text{A}$ $R_G = 3.3\Omega$ (External)		50	ns
$t_r$			173	ns
$t_{d(off)}$			203	ns
$t_f$			220	ns
$Q_{g(on)}$	$V_{GS} = \pm 5\text{V}, V_{DS} = 250\text{V}, I_D = 8\text{A}$		199	nC
$Q_{gs}$			18	nC
$Q_{gd}$			100	nC
$R_{thJC}$	TO-247			0.18 $^\circ\text{C/W}$
$R_{thCS}$			0.21	$^\circ\text{C/W}$

### Safe-Operating-Area Specification

Symbol	Test Conditions	Characteristic Values		
		Min.	Typ.	Max.
SOA	$V_{DS} = 500\text{V}, I_D = 0.5\text{A}, T_C = 75^\circ\text{C}, t_p = 5\text{s}$	250		W

### Source-Drain Diode

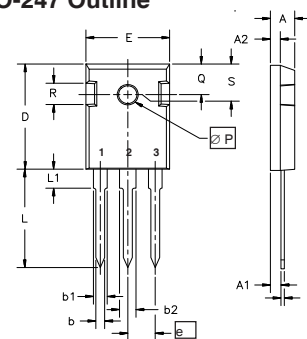
Symbol	Test Conditions ( $T_J = 25^\circ\text{C}$ , Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max.
$V_{SD}$	$I_F = 16\text{A}, V_{GS} = -10\text{V}$ , Note 1		0.8	1.3 V
$t_{rr}$	$I_F = 8\text{A}, -di/dt = 100\text{A}/\mu\text{s}$ $V_R = 100\text{V}, V_{GS} = -10\text{V}$		695	ns
$I_{RM}$			20	A
$Q_{RM}$			7	$\mu\text{C}$

Note 1. Pulse test,  $t \leq 300\mu\text{s}$ , duty cycle,  $d \leq 2\%$ .

IXYS Reserves the Right to Change Limits, Test Conditions, and Dimensions.

IXYS MOSFETs and IGBTs are covered by one or more of the following U.S. patents:	4,835,592	4,931,844	5,049,961	5,237,481	6,162,665	6,404,065 B1	6,683,344	6,727,585	7,005,734 B2	7,157,338B2
	4,860,072	5,017,508	5,063,307	5,381,025	6,259,123 B1	6,534,343	6,710,405 B2	6,759,692	7,063,975 B2	
	4,881,106	5,034,796	5,187,117	5,486,715	6,306,728 B1	6,583,505	6,710,463	6,771,478 B2	7,071,537	

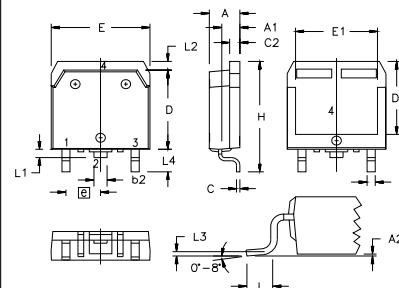
### TO-247 Outline



Terminals: 1 - Gate  
2 - Drain  
3 - Source

Dim.	Millimeter		Inches	
	Min.	Max.	Min.	Max.
A	4.7	5.3	.185	.209
A <sub>1</sub>	2.2	2.54	.087	.102
A <sub>2</sub>	2.2	2.6	.059	.098
b	1.0	1.4	.040	.055
b <sub>1</sub>	1.65	2.13	.065	.084
b <sub>2</sub>	2.87	3.12	.113	.123
C	.4	.8	.016	.031
D	20.80	21.46	.819	.845
E	15.75	16.26	.610	.640
e	5.20	5.72	0.205	0.225
L	19.81	20.32	.780	.800
L <sub>1</sub>		4.50		.177
∅P	3.55	3.65	.140	.144
Q	5.89	6.40	0.232	0.252
R	4.32	5.49	.170	.216
S	6.15	BSC	.242	BSC

### TO-268 Outline



Terminals: 1 - Gate  
2 - Drain  
3 - Source  
Tab - Drain

SYM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.193	.201	4.90	5.10
A <sub>1</sub>	.106	.114	2.70	2.90
A <sub>2</sub>	.001	.010	0.02	0.25
b	.045	.057	1.15	1.45
b <sub>2</sub>	.075	.083	1.90	2.10
C	.016	.026	0.40	0.65
C <sub>2</sub>	.057	.063	1.45	1.60
D	.543	.551	13.80	14.00
D <sub>1</sub>	.488	.500	12.40	12.70
E	.624	.632	15.85	16.05
E <sub>1</sub>	.524	.535	13.30	13.60
e	.215 BSC		5.45 BSC	
H	.736	.752	18.70	19.10
L	.094	.106	2.40	2.70
L <sub>1</sub>	.047	.055	1.20	1.40
L <sub>2</sub>	.039	.045	1.00	1.15
L <sub>3</sub>	.010 BSC		0.25 BSC	
L <sub>4</sub>	.150	.161	3.80	4.10

Fig. 1. Output Characteristics @  $T_J = 25^\circ\text{C}$

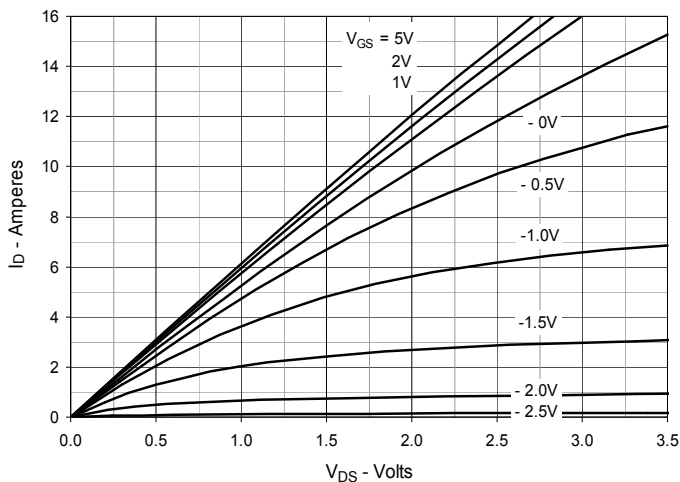


Fig. 2. Extended Output Characteristics @  $T_J = 25^\circ\text{C}$

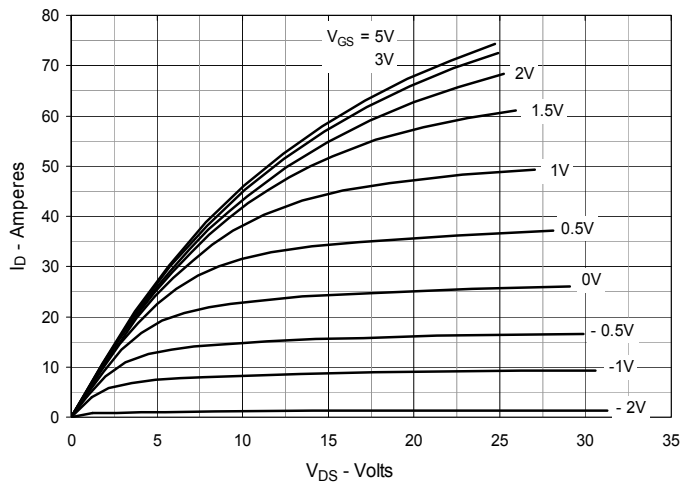


Fig. 3. Output Characteristics @  $T_J = 125^\circ\text{C}$

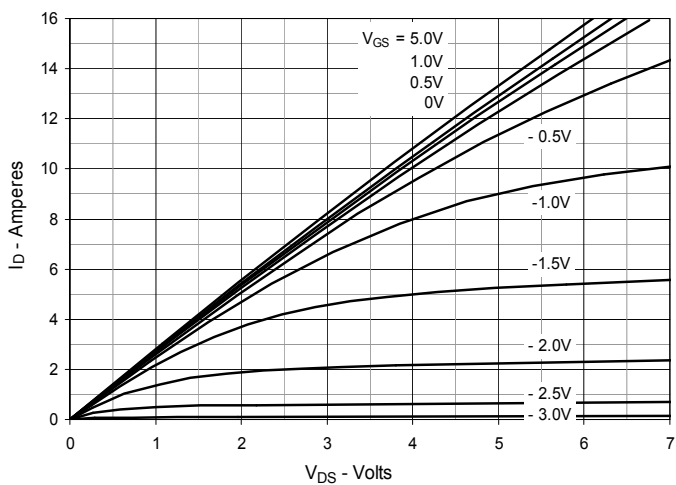


Fig. 4. Drain Current @  $T_J = 25^\circ\text{C}$

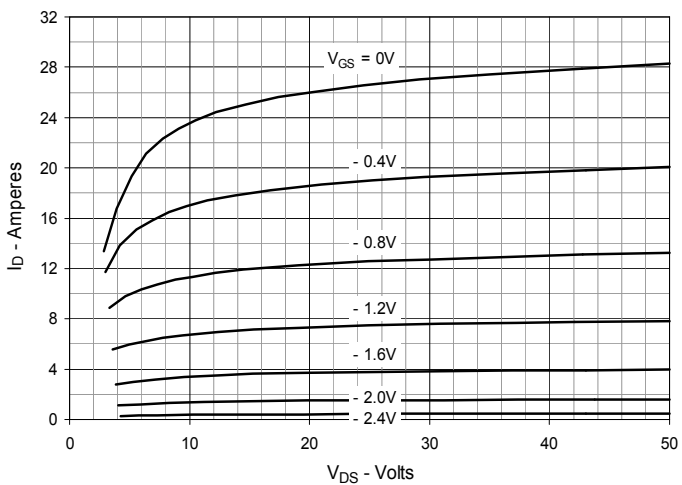


Fig. 5. Drain Current @  $T_J = 100^\circ\text{C}$

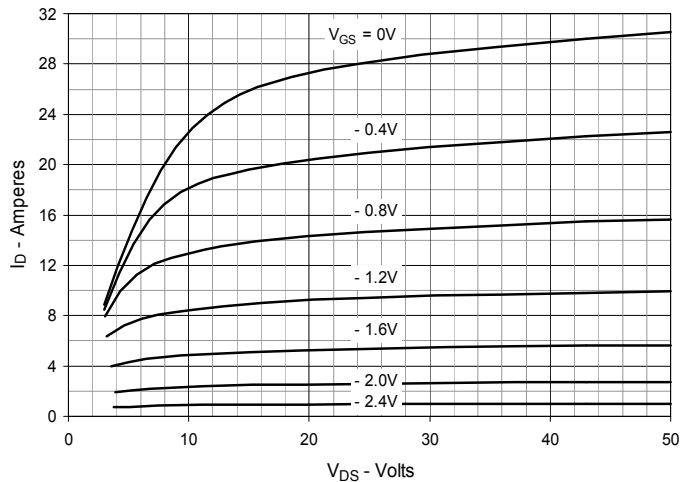
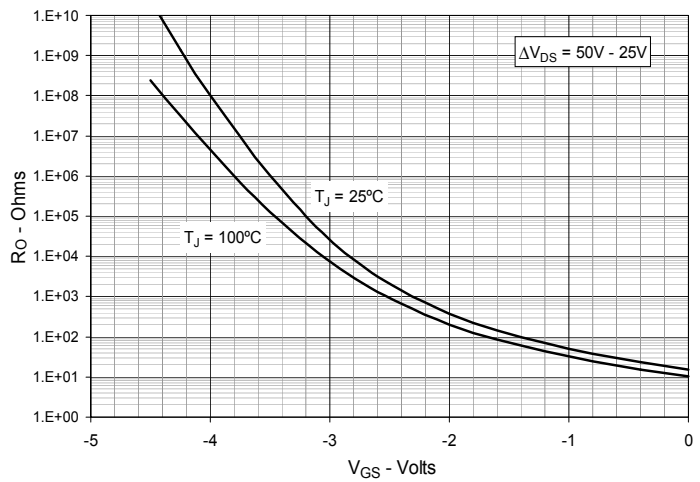
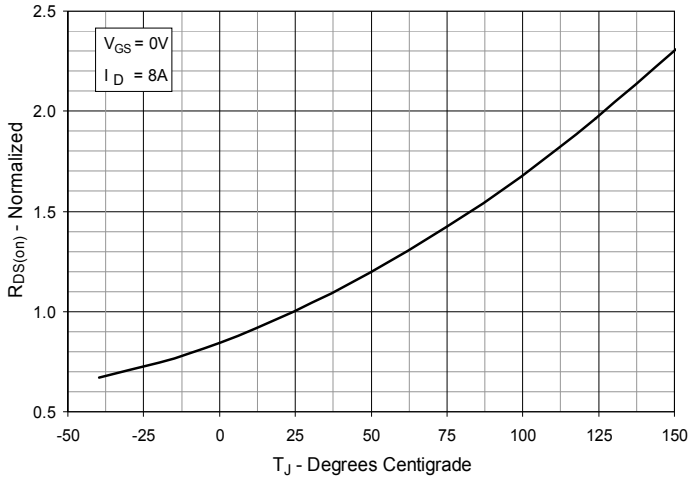


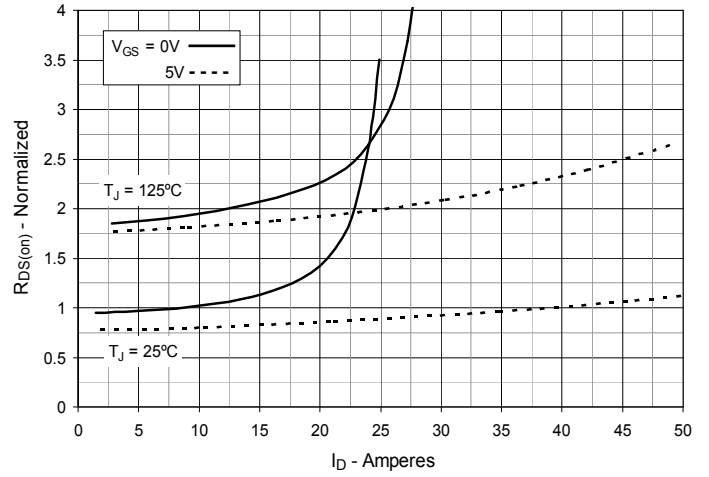
Fig. 6. Dynamic Resistance vs. Gate Voltage



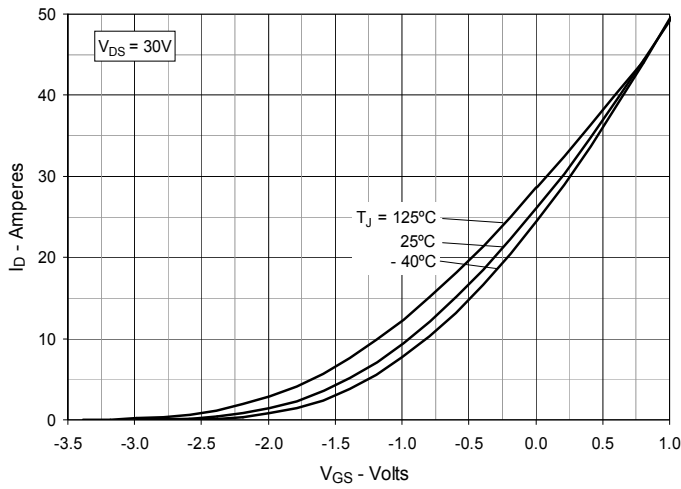
**Fig. 7. Normalized  $R_{DS(on)}$  vs. Junction Temperature**



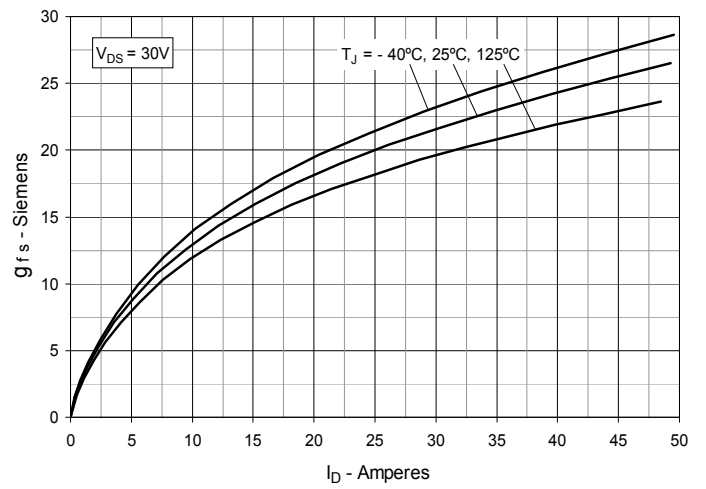
**Fig. 8.  $R_{DS(on)}$  Normalized to  $I_D = 8A$  Value vs. Drain Current**



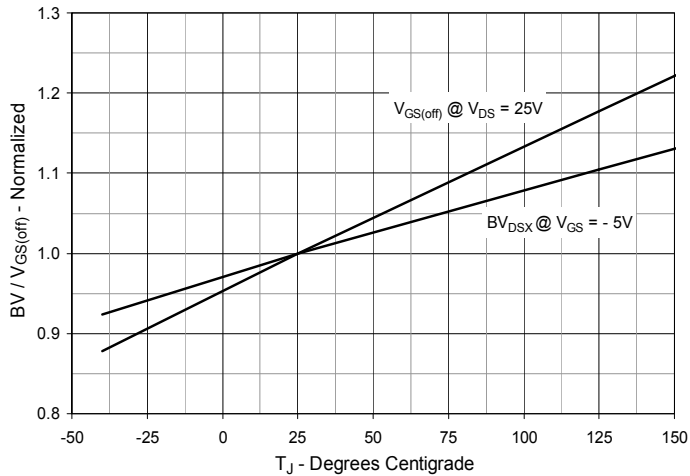
**Fig. 9. Input Admittance**



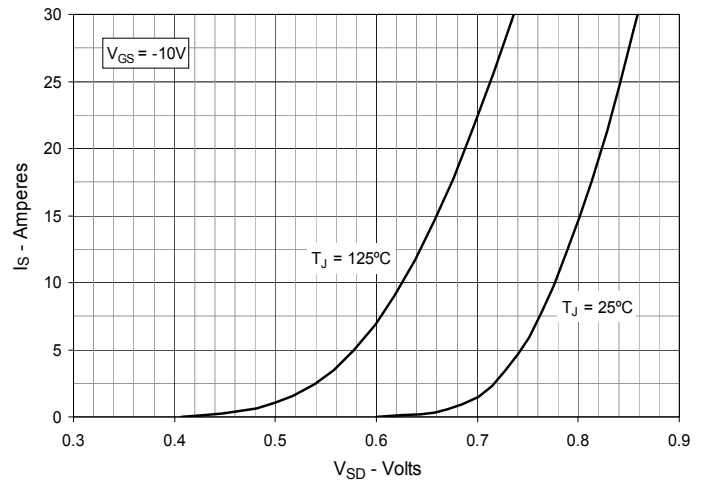
**Fig. 10. Transconductance**



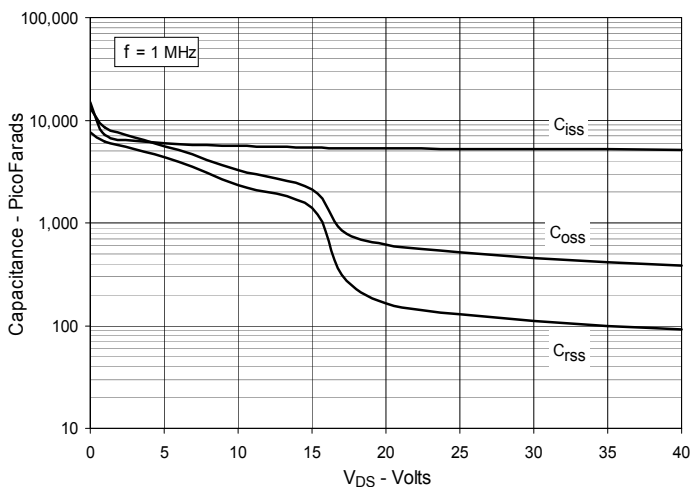
**Fig. 11. Breakdown and Threshold Voltages vs. Junction Temperature**



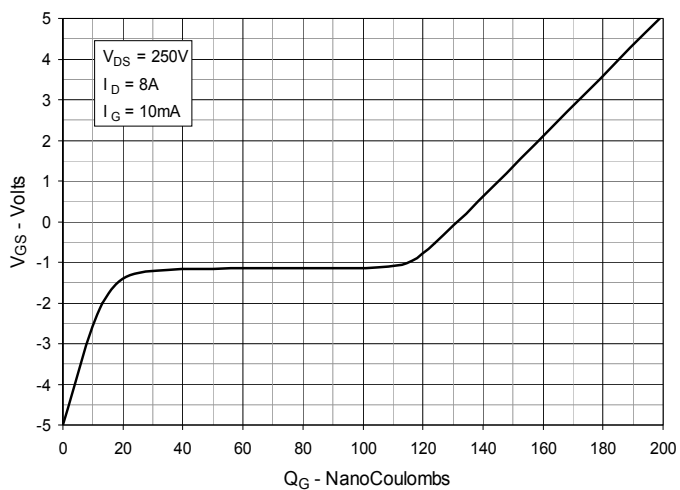
**Fig. 12. Forward Voltage Drop of Intrinsic Diode**



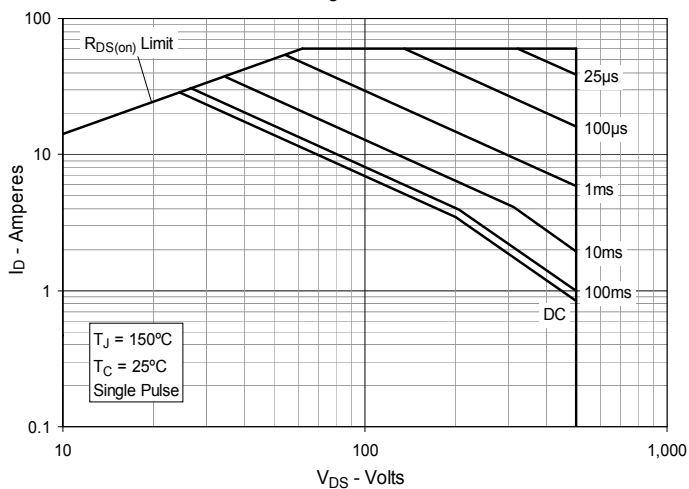
**Fig. 13. Capacitance**



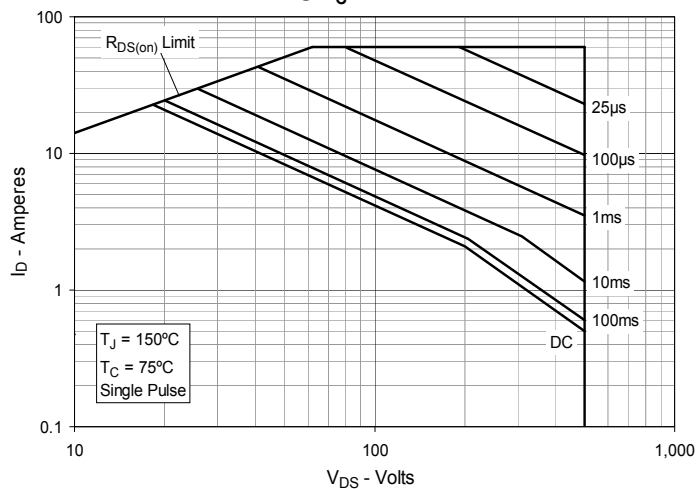
**Fig. 14. Gate Charge**



**Fig. 15. Forward-Bias Safe Operating Area  
@ T<sub>C</sub> = 25°C**



**Fig. 16. Forward-Bias Safe Operating Area  
@ T<sub>C</sub> = 75°C**



**Fig. 17. Maximum Transient Thermal Impedance**

